



INTERNATIONAL STANDARD



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**Electromagnetic compatibility (EMC) –
Part 4-36: Testing and measurement techniques – IEMI immunity test methods
for equipment and systems**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ELECTROMAGNETIC COMPATIBILITY (EMC) –

Part 4-36: Testing and measurement techniques – IEMI immunity test methods for equipment and systems

FOREWORD

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International Standard IEC 61000-4-36 has been prepared by subcommittee 77C: High-power transient phenomena, of IEC technical committee 77: Electromagnetic compatibility.

It forms part 4-36 of IEC 61000. It has the status of a basic EMC publication in accordance with IEC Guide 107.

The text of this standard is based on the following documents:

CDV	Report on voting
77C/231/CDV	77C/236/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61000 series, published under the general title *Electromagnetic compatibility (EMC)*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

Withdrawn

INTRODUCTION

IEC 61000 is published in separate parts according to the following structure:

Part 1: General

General considerations (introduction, fundamental principles)

Definitions, terminology

Part 2: Environment

Description of the environment

Classification of the environment

Compatibility levels

Part 3: Limits

Emission limits

Immunity limits (in so far as they do not fall under the responsibility of the product committees)

Part 4: Testing and measurement techniques

Measurement techniques

Testing techniques

Part 5: Installation and mitigation guidelines

Installation guidelines

Mitigation methods and devices

Part 6: Generic standards

Part 9: Miscellaneous

Each part is further subdivided into several parts, published either as International Standards or as technical specifications or technical reports, some of which have already been published as sections. Others will be published with the part number followed by a dash and a second number identifying the subdivision (example: IEC 61000-6-1).

ELECTROMAGNETIC COMPATIBILITY (EMC) –

Part 4-36: Testing and measurement techniques – IEMI immunity test methods for equipment and systems

1 Scope

This part of IEC 61000 provides methods to determine test levels for the assessment of the immunity of equipment and systems to intentional electromagnetic interference (IEMI) sources. It introduces the general IEMI problem, IEMI source parameters, derivation of test limits and summarises practical test methods.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61000-4-4, *Electromagnetic compatibility (EMC) – Part 4-4: Testing and measurement techniques – Electrical fast transient/burst immunity test*

IEC 61000-4-12, *Electromagnetic compatibility (EMC) – Part 4-12: Testing and measurement techniques – Ring wave immunity test*

IEC 61000-4-18, *Electromagnetic compatibility (EMC) – Part 4-18: Testing and measurement techniques – Damped oscillatory wave immunity test*